

**WHAT IS CLAIMED IS:**

1           1.       A system of manufacturing a liquid crystal display, the system comprising:  
2           a panel manufacturing unit for manufacturing a liquid crystal panel assembly including a  
3           thin film transistor (TFT) array panel, a color filter array panel, and a liquid crystal layer  
4           interposed between the TFT array panel and the color filter array panel;  
5           a printed circuit film bonding unit for bonding a printed circuit film on the panel  
6           assembly;  
7           a printed circuit board (PCB) bonding unit for bonding a PCB to the printed circuit film;  
8           and  
9           an inspection unit for inspecting the bonding of the printed circuit film on the panel  
10          assembly.

1           2.       The system of claim 1, wherein the printed circuit film comprises a tape carrier  
2           package.

1           3.       The system of claim 1, wherein the inspection unit comprises a differential  
2           camera or a differential scope.

1           4.       The system of claim 1, wherein the printed circuit film bonding unit bonds the  
2           printed circuit film on the panel assembly with an anisotropic conductive film (ACF).

1           5.       The system of claim 4, wherein the ACF comprises an adhesive containing a  
2           plurality of conductive particles.

1           6.       The system of claim 5, wherein the printed circuit film bonding unit bonds the  
2       printed circuit film on the panel assembly by compression.

1           7.       The system of claim 6, wherein the inspection unit detects dents generated by the  
2       compression.

1           8.       The system of claim 1, wherein the inspection unit detects alignment of the  
2       printed circuit film with the panel assembly.

1           9.       The system of claim 1, wherein the bonding inspection unit is incorporated into  
2       the printed circuit film bonding unit or the PCB bonding unit.

1           10.      The system of claim 1, wherein the bonding inspection unit comprises two sub-  
2       units for inspection before and after the bonding of the PCB, respectively.

1           11.      The system of claim 10, wherein one of the sub-units of the bonding inspection  
2       unit is incorporated into the printed circuit film bonding unit and the other of the sub-units of the  
3       bonding inspection unit is incorporated into the PCB bonding unit.

1           12.      A method of manufacturing a liquid crystal display, the method comprising:  
2       manufacturing a liquid crystal panel assembly;  
3       bonding a printed circuit film on the panel assembly;  
4       inspecting the bonding of the printed circuit film on the panel assembly; and  
5       bonding a printed circuit board (PCB) to the printed circuit film.

1           13.     The method of claim 12, wherein the inspection is performed before the bonding  
2     of the PCB.

1           14.     The method of claim 13, further comprising:  
2           inspecting the bonding of the printed circuit film on the panel assembly again after the  
3     bonding of the PCB.

1           15.     The method of claim 12, wherein the inspection is performed after the bonding of  
2     the PCB.

1           16.     The method of claim 12, wherein the printed circuit film comprises a tape carrier  
2     package.

1           17.     The method of claim 12, wherein the inspection is performed using a differential  
2     camera or a differential scope.

1           18.     The method of claim 12, wherein the printed circuit film is bonded on the panel  
2     assembly with an anisotropic conductive film (ACF) containing a plurality of conductive  
3     particles.

1           19.     The method of claim 18, wherein the bonding of the printed circuit film is  
2     performed by thermocompression.

1           20.    The method of claim 19, wherein the inspection detects dents generated by the  
2   thermocompression.